



Material Content Data Sheet



Sales Product Name		TLE4998C3		Issued		1. August 2018			
MA#		MA000873790							
Package		PG-SSO-3-10		Weight*		142.97 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.851	2.69	2.69	26940	26940	
leadframe	inorganic material	silicon	7440-21-3	0.020	0.01		138		
		non noble metal	titanium	7440-32-6	0.099	0.07		692	
		non noble metal	chromium	7440-47-3	0.297	0.21		2076	
wire	noble metal	non noble metal	copper	7440-50-8	98.494	68.90	69.19	688941	691847
		noble metal	gold	7440-57-5	0.047	0.03	0.03	329	329
		organic material	carbon black	1333-86-4	0.357	0.25		2497	
encapsulation	plastics	epoxy resin	-	4.511	3.16		31553		
		inorganic material	silicondioxide	60676-86-0	27.585	19.30	22.71	192951	227001
leadfinish	non noble metal	tin	7440-31-5	5.779	4.04	4.04	40426	40426	
plating	noble metal	silver	7440-22-4	0.604	0.42	0.42	4222	4222	
glue	plastics	epoxy resin	-	0.264	0.18		1847		
		noble metal	silver	7440-22-4	1.056	0.74	0.92	7388	9235
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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